

产品规格书

SPECIFICATIONS FOR PRODUCT

产品类型	TYPE	:	SMD3225
产品规格	SPEC	:	24MHz/3225/12PF/10PPM AEC-Q200
产品型号	P/N	:	AD-CJ13-240001210C30
日期	DATE	:	2022/04/02

核准及签名			部プ
R&D APPR.	SIGNATURED		DEPT.
拟制	审核	批准	频率器件事业部
ISSUE	CHECK	APPROVAL	
Ivan	Abbey	Ken	
2022/04/02	2022/04/02	2022/04/02	

苏 K 江 묩 科 技 股 份 有 限 公 司 JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD. 地址:中国江苏省南京江北新区产业技术研创园江淼路88号腾飞大厦C座13楼 Add: 13Th Floor, C Block, Tengfei Building, No. 88 Jiangmiao Rd. Pukou District, Nanjing City, Jiangsu Province, China

JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO., LTD. JSCJ <u>SMCE3225 4 pads Crystal Resonator</u>

AD-CJ13-240001210C30

- 1. Scope:
- 1.1 This specification applies to the RoHS/SONY compliance quartz crystal unit with a frequency of 24MHz which will be used in crystal oscillator applications.
- 1.2 AEC-Q200 qualified
- 2. Construction:
- 2.1 Type of Quartz Resonator: SMCE3225 4pads

3. Electrical Characteristics

3.1	Nominal Frequency(f):	24MHz
3.2	Load Capacitance(C _L):	12pF
3.3	Frequency Tolerance($\triangle f/f$):	±10ppm
3.4	Frequency Temperature Stability:	±30ppm(Ref.@25℃)
3.5	Resonance Resistance(ohm):	40ohms Max
3.6	Osc mode:	Fundamental mode
3.7	Shunt Capacitance(C ₀):	<2pF
3.8	Drive Level(D _L):	<100µW
3.9	Operating Temperature Range(T _{OPR}):	-40 to + 105
3.10	Storage Temperature Range(T _{STG}):	-55 to + 125°C
3.11	Insulation Resistance(IR):	>500 M ohms
3.12	Aging(△f _A):	±3ppm per Year

4. Reliability Specifications

This is the quality control and quality assurance and reliability tests performance data for the RoHS/

AEC-Q200 compliance 24MHz SMCE3225 4pads crystal resonators

related to the specification and approval sheet provided by JSCJ.

Standard test condition (TEMP.: 20±5°C. Relative humidity: 65±20%)

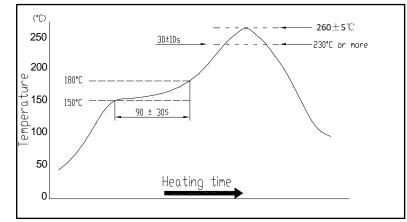
For any discrepancy in GO/NG, test will be done at TEMP.25±2°C, R.H. 65±5%.

NO.	PROCESS	SPECIFICATION	TEST METHOD
4.1	Temperature Cycle	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤5ohms.	1000 cycles from -40°C to 125°C. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.2	High Temperature Storage	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤5ohms.	Spending 1000 hrs at 85°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.3	Biased Humidity	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤5ohms.	Spending 1000 hrs at 85 °C \pm 3 °C, with 85%R.H, Then keep the DUT in dry oven at 25 \pm 5 °C for 24 hour. Measurement taken after DUT being left at room temperature for 1 to 2 hours.
4.4	Operational Life	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤5ohms.	Spending 1000 hrs at 125°C±3°C constant temperature. Measurement taken after DUT being left at room temperature for 24±2 hours.
4.5	Vibration	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤5ohms.	Apply 1.52mm vibration at sweep frequency $10\sim$ 2000Hz, 5g's for 20min 12 cycles in each direction of 3 axis. Measurement taken after 1 hour.
4.6	Mechanical Shock	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤5ohms.and exhibit no visible damage.	Peak 100gal, normal width 6ms half sine wave form, 3.7m/s, 3 cycles / direction. Measurement taken after 1 hour.
4.7	Solderability	Terminals shall be covered more then 95% with solder.	Passed through the re-flow oven under the following condition. Preheat 150 to 180° C for 60 to 120sec, and soldering time for 20s ± 5s at 235°C, peak soldering time for 5s ±0.5s betweein 240 and 250°C. There is no need to do functional test. 8-12X magnifier.
4.8	Terminal Strength	No visible damage	Mount on a glass-epoxy board (100x50x1.6mm), then bend to 2mm displacement (velocity 1mm/sec) and keep for 5 seconds. or pulling force 1.8kg for at least 60 seconds.
4.9	Resistance to Soldering Heat	Frequency change after test ≤± 5ppm.Resonance resistance change after test ≤5ohms.	Passed through the re-flow oven under the following condition. Preheat 150 to 180°C for 60 to 120sec, and sodering time for 60s max at 235°C, peak soldering time for 10s max at 265°C max. Measurement taken after DUT being left at room temperature for at least 2 hours.
4.10	OTHERS		

5. Recommended Reflow soldering condition (SMD)

Solder profile

Peak: 260±5°C Soldering zone: 230°C or more, 30±10s. Pre-heating zone 1: 150 \sim 180°C, 90±30s

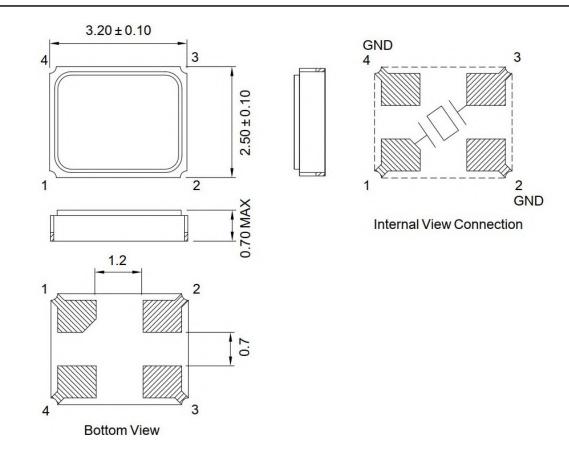


Temperature profile for reflow soldering

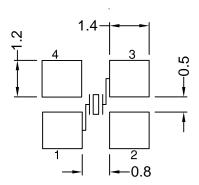
6. Soldering iron method

Bit temperature: 350 ± 10 °C Application time of soldering iron:3+1 s. For other procedures, refer to IEC 60068-2-20.

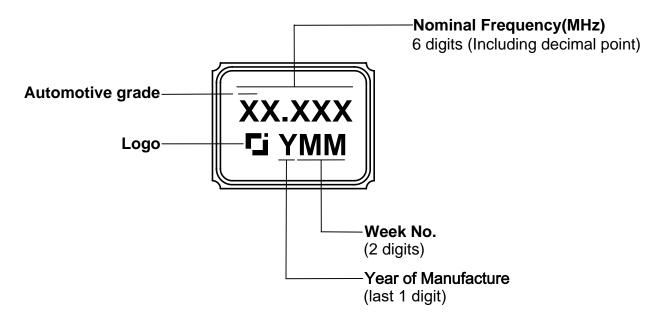
Package Outline Dimensions



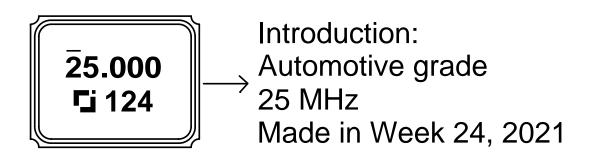
Suggested Pad Layout



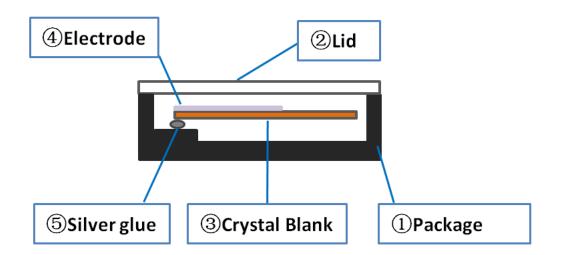
Procedure: Laser



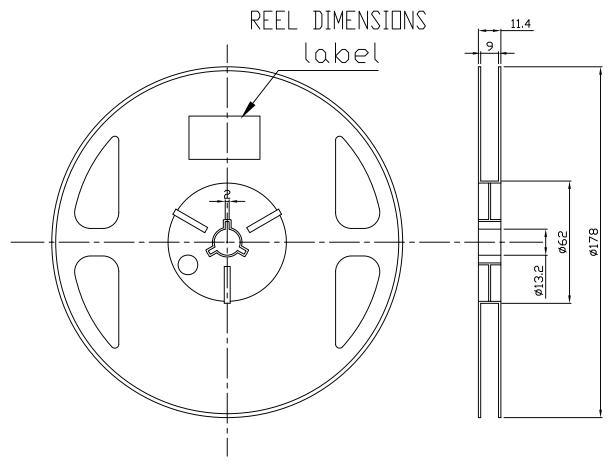
For example:



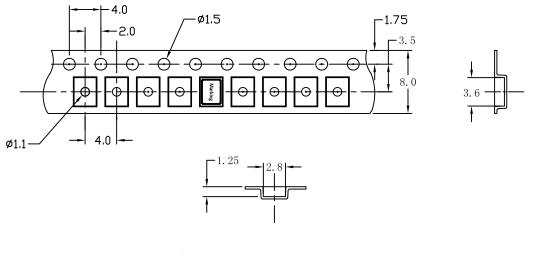
Inside Structure



No.	Components	Materials	
1	Package	Ceramic(Al ₂ O ₃)	
2	Lid	KV(Fe/Ni/Co)	
3	Crystal blank	SiO ₂	
4	Electrode	Ag、 Cr	
5	Silver glue	Ag、CH ₃ OH、SiO ₂	



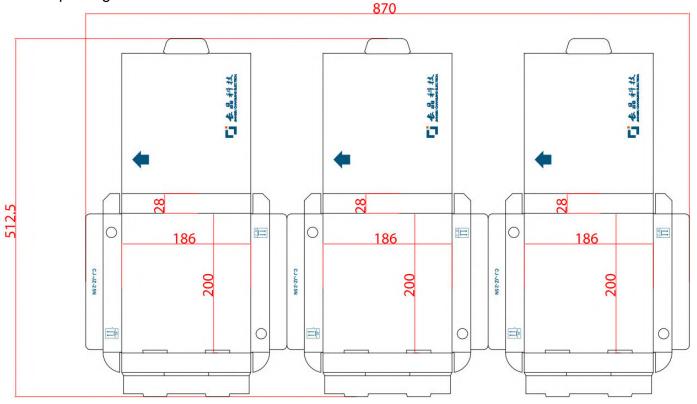
EMBOSSED TYPE DIMENSIONS



USER FEED DIRECTION

Package

Inside package



Outside package

◄	► 325 mm		420 mm	
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